Electronic Pate	nt App	lication Fe	e Transmit	tal				
Application Number:	105	10581851						
Filing Date:	22-1	22-Feb-2007						
Title of Invention:	Bon	Bonding Apparatus and Bonding Method						
First Named Inventor/Applicant Name:	Hac	Hachiya Takeuchi						
Filer:	Jose	Joseph W. Price/Sharon Farnus						
Attorney Docket Number:	425	42598-4100						
Filed as Large Entity								
U.S. National Stage under 35 USC 371 Fili	ing Fees	į						
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:	6							
Independent claims in excess of 3		1614	1	220	220			
Miscellaneous-Filing:			I					
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension of Times								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 1 month with \$0 paid	1251	1	130	130
Miscellaneous:				
	Total in USD (\$)			350